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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Silicon Carbide Power Schottky Diode

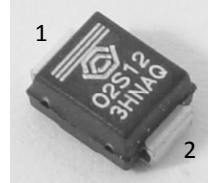
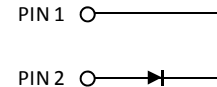
V_{RRM}	=	1200 V
$I_F (T_C = 25^\circ\text{C})$	=	5 A
$I_F (T_C \leq 150^\circ\text{C})$	=	2 A
Q_C	=	9 nC

Features

- Industry's leading low leakage currents
- 175 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of V_F
- Extremely fast switching speeds
- Superior figure of merit Q_C/I_F

Package

- RoHS Compliant


SMB / DO – 214AA


Advantages

- Low standby power losses
- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Low reverse recovery current
- Low device capacitance
- Low reverse leakage current at operating temperature

Applications

- Power Factor Correction (PFC)
- Switched-Mode Power Supply (SMPS)
- Solar Inverters
- Wind Turbine Inverters
- Motor Drives
- Induction Heating
- Uninterruptible Power Supply (UPS)
- High Voltage Multipliers

Maximum Ratings at $T_j = 175^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		1200	V
Continuous forward current	I_F	$T_C = 25^\circ\text{C}$	5	A
Continuous forward current	I_F	$T_C \leq 150^\circ\text{C}$	2	A
RMS forward current	$I_{F(RMS)}$	$T_C \leq 150^\circ\text{C}$	3	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$ $T_C = 150^\circ\text{C}, t_p = 10\text{ ms}$	18 15	A
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25^\circ\text{C}, t_p = 10\ \mu\text{s}$	100	A
I^2t value	$\int i^2 dt$	$T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$ $T_C = 150^\circ\text{C}, t_p = 10\text{ ms}$	1.6 1.1	A ² s
Power dissipation	P_{tot}	$T_C = 25^\circ\text{C}$	65	W
Operating and storage temperature	T_j, T_{stg}		-55 to 175	°C

Electrical Characteristics at $T_j = 175^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	V_F	$I_F = 2\text{ A}, T_j = 25^\circ\text{C}$		1.5	1.8	V
		$I_F = 2\text{ A}, T_j = 175^\circ\text{C}$		2.6	3.0	
Reverse current	I_R	$V_R = 1200\text{ V}, T_j = 25^\circ\text{C}$		5	50	μA
		$V_R = 1200\text{ V}, T_j = 175^\circ\text{C}$		10	100	
Total capacitive charge	Q_C	$I_F \leq I_{F,MAX}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $T_j = 175^\circ\text{C}$	$V_R = 400\text{ V}$	9		nC
			$V_R = 960\text{ V}$	14		
Switching time	t_s		$V_R = 400\text{ V}$ $V_R = 960\text{ V}$	< 17		ns
Total capacitance	C	$V_R = 1\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		131		pF
		$V_R = 400\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		12		
		$V_R = 1000\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		8		

Thermal Characteristics

Thermal resistance, junction - case	R_{thJC}	2.3	°C/W
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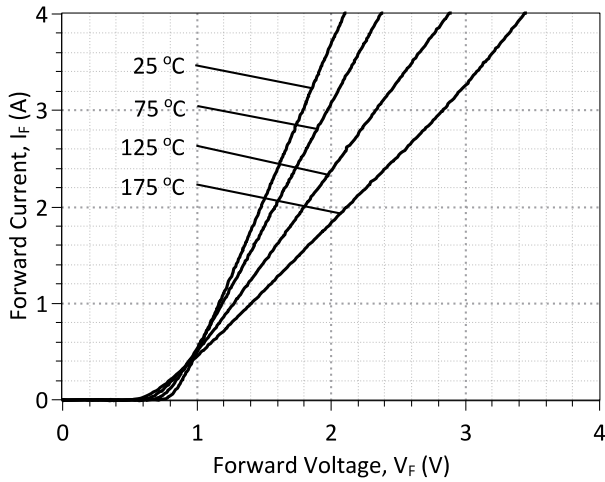


Figure 1: Typical Forward Characteristics

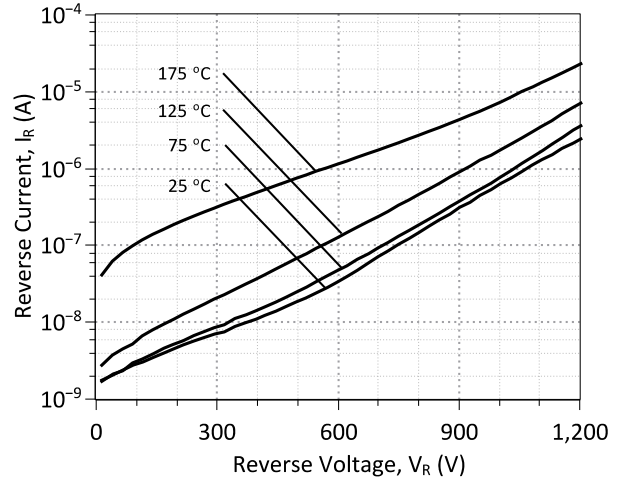


Figure 2: Typical Reverse Characteristics

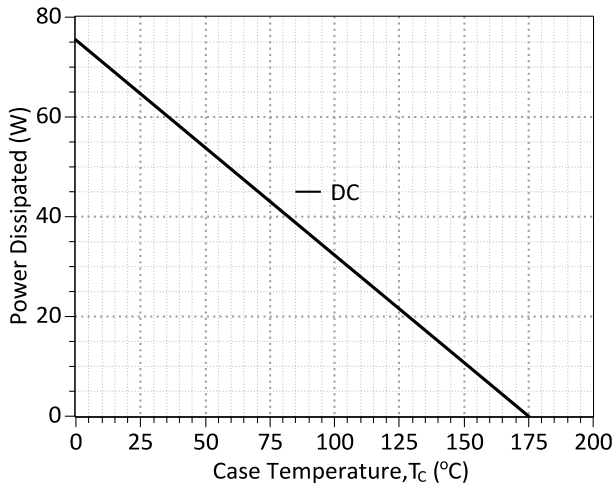
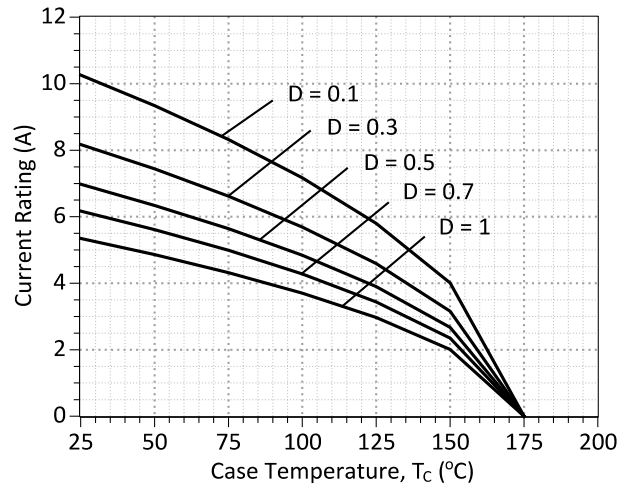


Figure 3: Power Derating Curve



**Figure 4: Current Derating Curves (D = t_p/T , $t_p = 400 \mu s$)
(Considering worst case Z_{th} conditions)**

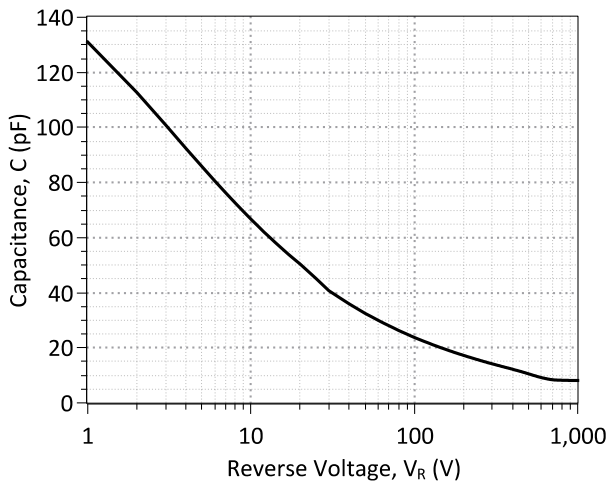


Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

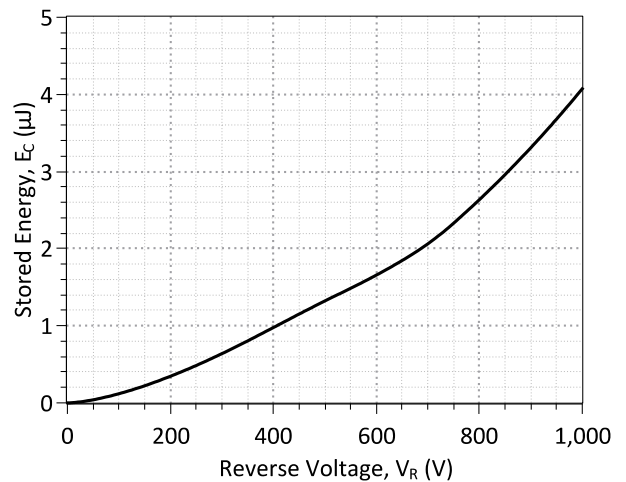


Figure 6: Typical Capacitive Energy vs Reverse Voltage Characteristics

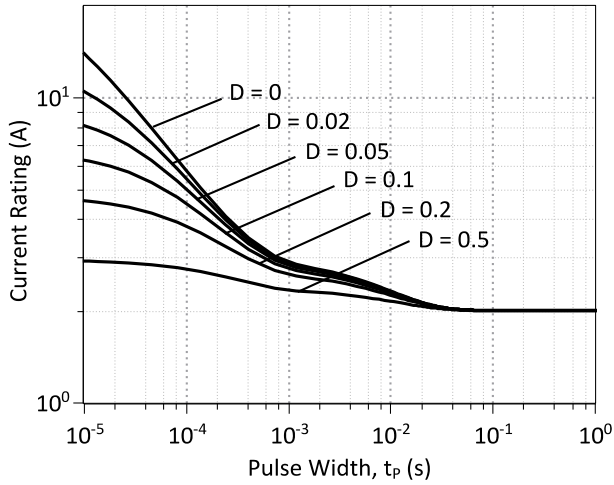


Figure 7: Current vs Pulse Duration Curves at $T_c = 160\text{ }^\circ\text{C}$

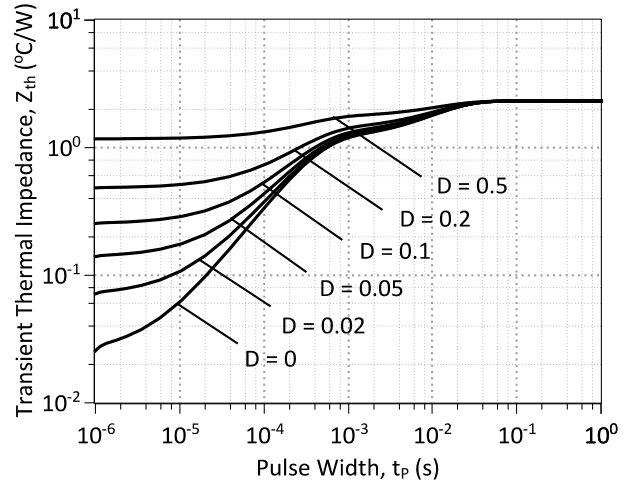
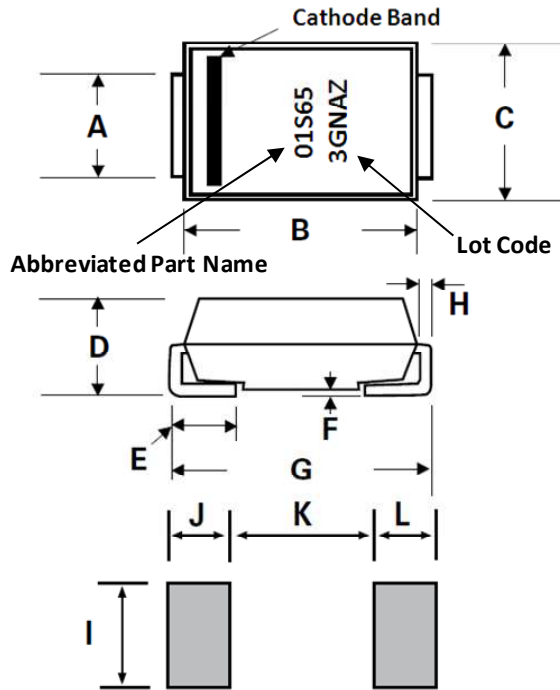


Figure 8: Transient Thermal Impedance

Package Dimensions:

SMB / DO - 214AA

PACKAGE OUTLINE



Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.077	0.086	1.950	2.200
B	0.160	0.180	4.060	4.570
C	0.130	0.155	3.300	3.940
D	0.084	0.096	2.130	2.440
E	0.030	0.060	0.760	1.520
F	-	0.008	-	0.203
G	0.205	0.220	5.210	5.590
H	0.006	0.012	0.152	0.305
I	0.089	-	2.260	-
J	0.085	-	2.160	-
K	-	0.107	-	2.740
L	0.085	-	2.160	-

NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

Revision History

Date	Revision	Comments	Supersedes
2014/08/26	1	Updated Electrical Characteristics	
2013/09/09	0	Initial release	

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SPICE Model Parameters

This is a secure document. Please copy this code from the SPICE model PDF file on our website (http://www.genesicsemi.com/images/products_sic/rectifiers/GB02SLT12-214_SPICE.pdf) into LTSPICE (version 4) software for simulation of the GB02SLT12-214.

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*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:   1.0           $
*      $Date:      09-SEP-2013   $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*
*      COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
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*
*      These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
*      OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
*      TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
*      PARTICULAR PURPOSE."
*      Models accurate up to 2 times rated drain current.
*
*      Start of GB02SLT12-214 SPICE Model
*
.SUBCKT GB02SLT12 ANODE KATHODE
D1 ANODE KATHODE GB02SLT12
D2 ANODE KATHODE GB02SLT12_PIN
.MODEL GB02SLT12 D
+ IS      2.05E-15      RS      0.282
+ TRS1    0.0054       TRS2    3E-05
+ N       1            IKF     251
+ EG      1.2          XTI     -1.8
+ CJO     1.61E-10     VJ      0.4508
+ M       1.586        FC      0.5
+ TT      1.00E-10     BV      1200
+ IBV     1.00E-03     VPK     1200
+ IAVE    2            TYPE    SiC_Schottky
+ MFG     GeneSiC_Semi
.MODEL GB02SLT12_PIN D
+ IS      1.54E-25     RS      0.39
+ TRS1    -0.003      N       3.941
+ EG      3.23        IKF     19
+ XTI     0           FC      0.5
+ TT      0           BV      1200
+ IBV     1.00E-03     VPK     1200
+ IAVE    10          TYPE    SiC_PiN
.ENDS
*
*      End of GB02SLT12-214 SPICE Model
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